

PCN#20200825000.1 Qualification of TFME as an additional assembly site for select Devices Change Notification / Sample Request

Date: August 26, 2020 To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

20200825000.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

DRV5055A1QDBZT DRV5055A4QDBZT

null null

Technical details of this Product Change follow on the next page(s).

PCN Number: 20200825000.1 PCN Date: Aug 26 2020									
Title: Qualification of TFME as an additional assembly site for select Devices									
Customer Contact: PCN Manager Dept: Quality Services									
Drenered 1 st Chi	n Data:	Nevr			Estimate			provided at	
Proposed 1 st Ship Date: Nov 24 2020 Estimated Sample Date provided at sample Availability: sample request									
Change Type:									
Assembly Site	9			Design			Wafer Burr	np Site	
Assembly Pro	cess			Data S	heet		Wafer Burr	np Material	
Assembly Mat					umber change		Wafer Burr		
Mechanical Sp				Fest S			Wafer Fab Site		
Packing/Shipp	oing/Labe	ling	[]]	Fest Pi	rocess			Wafer Fab Materials	
							Wafer Fab	Process	
				PCN	Details				
Description of C	nange:								
Assembly site for	Texas Instruments Incorporated is announcing the qualification of NFME as an alternate Assembly site for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:								
					HNA		TFME		
Ма	old Comp	ound			SID#450179	SI	D# R-27		
Reason for Chan	· · ·			I					
Supply continuity	-								
	act on Fo	orm. Fit	t. Fun	oction	, Quality or Relia	bility	v (nositive	/ negative):	
None		,	c, i an		, quanty of Rena	bille) (positive	/ negutive):	
Anticipated impa	act on M	aterial	Decla	aratio	n				
No Impact to the Material DeclarationMaterial DeclarationMaterial DeclarationMaterial DeclarationMaterial DeclarationMaterial Declaration data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp						ing the e revised			
Changes to prod	uct iden	tificatio	on re	sultin	g from this PCN:				
Assembly Site					Assembly Country Code (23L)			sembly City	
HNA		HNT			THA	/	Ayutthaya		
TFME NFM				CHN			Economic Development Zone		
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT OPT: ITEM: 39 LBL: 5A (L)T0:1750 (not actual product label) (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS									

Product Affected:

DRV5055A1QDBZR	DRV5055A2QDBZR	DRV5055A3QDBZR	DRV5055A4QDBZR	
DRV5055A1QDBZT	DRV5055A2QDBZT	DRV5055A3QDBZT	DRV5055A4QDBZT	



TI Confidential Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

•			Duta Dispia	yeu us. Humber	of lots / Total s				
Туре	Test Name / Condition	Duration	Qual Device: <u>DRV5055A1QDBZ</u> <u>R</u>	Qual Device: <u>DRV5055A2QDBZ</u> <u>R</u>	Qual Device: <u>DRV5055A3QDBZ</u> <u>R</u>	Qual Device: <u>DRV5055A4QDBZ</u> <u>R</u>	QBS Product Reference: <u>DRV5055A3QDB</u> <u>Z</u>	QBS Product Reference: <u>DRV5055A4QDB</u> <u>Z</u>	QBS Process Reference: <u>DRV5013ADEDBZRQ</u> <u>1</u>
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	3/231/0
CDM	ESD - CDM - Q100	1000	-	-	-	-	-	-	1/3/0
CDM	ESD - CDM - Q100	1500 V	-	-	1/3/0	-	1/3/0	-	-
ED	Auto Electrical Distributions	Cpk>1.33 Ppk>1.67 Room, hot, and cold test	-	-	-	-	-	-	1/30/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	1/30/0	-	-	-
ELFR	Early Life Failure Rate, 150C	48	-	-	-	-	-	-	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	1/78/0	3/231/0
HBM	ESD - HBM - Q100	2500 V	-	-	-	-	1/3/0	-	1/3/0
HBM	ESD - HBM - Q100	4000 V	-	-	1/3/0	-	-	-	-
HTOL	Life Test, 150C	1000	-	-	-	-	-	-	3/231/0
HTOL	Life Test, 150C	300	-	-	-	-	-	1/77/0	-
HTOL	Life Test, 150C	408	-	-	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 175C	1000	-	-	-	-	-	-	1/45/0
HTSL	High Temp Storage Bake 175C	500	-	-	-	-	-	1/77/0	1/45/0
LU	Latch-up	(Per JESD78)	-	-	1/6/0	-	1/6/0	-	1/6/0
MQ	Manufacturabilit y (Assembly)	(per mfg. Site specification)	-	-	1/Pass	-	-	-	-
MQ	Manufacturabilit y (Auto Assembly)	(per automotive requirements)	-	-	-	-	-	-	1/Pass
MSL	Moisture Sensitivity, L2	Elec/25C	-	-	1/12/0	-	-	-	-
SD	Pb Free Surface Mount Solderability	Pb Free/Solder-	-	-	-	-	-	-	1/15/0
тс	Temperature Cycle, -65/150C	2000	-	-	-	-	-	-	3/231/0
тс	Temperature Cycle, -65/150C	500 Cycles	-	-	1/77/0	-	-	1/77/0	3/231/0
UHAS T	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	-
WBP	Bond Pull	0 Hr	-	-	-	-	-	-	1/5/0

Туре	Test Name / Condition	Duration	QBS Package Reference: <u>TMUX1119DCK</u>	QBS Package Reference: <u>TPS61322DBZ</u>
AC	Autoclave 121C	168 Hours	3/231/0	-
AC	Autoclave 121C	96 Hours	3/231/0	-
CDM	ESD - CDM	1500 V	-	1/3/0
CDM	ESD - CDM	2000 V	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	-	1/Pass
HAST	Biased HAST, 130C/85%RH	192 Hours	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-
HBM	ESD - HBM	4000 V	-	1/3/0
HBM	ESD - HBM	6000 V	1/3/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	600 Hours	3/231/0	-
HTSL	High Temp Storage Bake 170C	630 Hours	-	3/231/0
LU	Latch-up	(Per JESD78)	1/6/0	1/6/0
MQ	Manufacturability	(per mfg. Site specification)	-	3/Pass
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/Pass	-
MSL	Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	-	3/36/0
MSL	Moisture Sensitivity, JEDEC	Level 1-260C	1/12/0	-
TC	Temperature Cycle, -65/150C	1000 Cycles	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	750 Cycles	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	192 Hours	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0
VM	Bond Pad Crater Check	Completed	3/Pass	-
WBP	Bond Pull	Wires	3/228/0	-
WBS	Wire Bond Shear	Wires	3/228/0	-
YLD	FTY and Bin Summary	-	-	3/Pass

- QBS: Qual By Similarity - Qual Device DRV5055A2QDBZR is gualified at LEVEL2-260C

- Qual Device DRV5055A3QDBZR is qualified at LEVEL2-260C - Qual Device DRV5055A1QDBZR is qualified at LEVEL2-260C

Qual Device DRV5055A4QDBZR is qualified at LEVEL2-260C

Preconditioning was performed for Autoclave Unbiased HAST THB/Biased HAST Temperature Cycle Thermal Shock and HTSL as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/14 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 150C/14 Hours, and 170C/420 Hours
- The following are equivalent TEMP Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

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